

Platform Architect for Multi-Die

Early architecture exploration of multi-die designs

Overview

Synopsys Platform Architect for Multi-Die is a SystemC™ standards-based performance and power analysis tool for early architecture exploration of multi-die designs. It accounts for the interdependencies between multiple dies (also referred to as chiplets) within multi-die systems.

Platform Architect for Multi-Die helps optimize hardware-software partitioning, IP selection and configuration, interconnect and memory configuration, and power under consideration of the die-to-die interfaces. The solution includes a die-to-die model, including UCle, as part of its library portfolio to compose a multi-die system for early architecture exploration.

Platform Architect for Multi-Die is part of the comprehensive Synopsys Multi-Die System Solution for accelerated heterogeneous integration and system disaggregation. The solution, including EDA and IP products, enables early architecture exploration, rapid software development and system validation, efficient die/package co-design, robust and secure die-to-die connectivity, and enhanced manufacturing and reliability.



